ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INCLUSTRIES	nposition De 5. IPC, Bannockl Pan-American co	claration ourn, Illinois. A opyright conver	Il rights reserved untions.	under both	This docume level parts, th	ent is a declaration he declaration er	on of the substan acompasses all lo	ces within the m wer level mater	anufacturer li ials for which	sted item. Note: the manufacture	if the item is an as r has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distribution								us Materials a	rials and Mfg Information			
upplier Information													
ompany name*	Company un	Company unique ID			Unique ID Authority				Response Date*				
nsemi									2023-06-08				
Contact Name Title - C			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Pr			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title			Title - Representative			Phone - Representative*			En	Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	GBU6D	BU6D BR GBU4L GP		N 6A 200V		2023-06-08 TSCBE		TSCBE		3995.245	mg	Each	
Ianufacturing Proccess Infor	nation												
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		ature Max Tim	e at Peak Ten	perature Num	ber of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		seconds 3				
omments													
or more information regarding mate	rial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier rot a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of hat agreement, will be the sole and exclusivesource of the Supplier's Iiability and the Company's remedies for issues that arise regarding information the Supplier provides in th											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	15.0	mg	Supplier	Silicon (Si)	7440-21-3		15	mg
Die Attach Solder	15.025	mg	Supplier	Silver (Ag)	7440-22-4		0.3756	mg
			А	Lead (Pb)	7439-92-1	7a	13.8981	mg
			Supplier	Tin (Sn)	7440-31-5		0.7512	mg
Lead Frame	1799.6	mg	Supplier	Iron (Fe)	7439-89-6		2.6994	mg
			Supplier	Copper (Cu)	7440-50-8		1796.0009	mg
			Supplier	Phosphorus (P)	7723-14-0		0.8998	mg
Mold Compound-Black	2160.0	mg		Epoxy resin	proprietary data		108	mg
			Supplier	Phenolic Resin	Proprietary Data		162	mg
			Supplier	Carbon Black (C)	1333-86-4		10.8	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		324	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1555.2001	mg
Plating	5.62	mg	Supplier	Tin (Sn)	7440-31-5		5.62	mg